

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
RESUBMIT DOCUMENT ID:	504142882
CONVEYING PARTY DATA	
Name	Execution Date
MAKI MORI	02/14/2014
SHUNICHI KASAHARA	02/17/2014
OSAMU SHIGETA	02/14/2014
SEIJI SUZUKI	02/19/2016
RYO FUKAZAWA	02/20/2014
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15376052
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DATE SIGNED:	02/01/2017
Total Attachments: 2	

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ASSIGNMENT

WHEREAS, I, as below named inventor, residing in the addresses stated next to my names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **VOICE CONTROL DEVICE, VOICE CONTROL METHOD AND PROGRAM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, in and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries:

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Agreement Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest therein:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its assignees, as ASSIGNEE or its assignees, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to prepare, execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patents, and or, for obtaining any rehear or rehears of any Letters Patent which may be granted for my aforesaid invention, or the ASSIGNEE hereafter requires and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorneys of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.: PCT/JP2014/085291, International Filing Date: 2014.08.23

This assignment executed on the dates indicated below:

MAKI MORI
Name of first or sole inventor
TOKYO, JAPAN
Residence of first or sole inventor
Maki Mori
Signature of first or sole inventor

Execution date of U.S. Patent Application

February 14, 2014
Date of this assignment

SHUNICHI KASAHARA
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Execution date of U.S. Patent Application

February 17, 2014
Date of this assignment

OSAMU SHIGETA
Name of third inventor
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Residence of third inventor
Osamu Shigeta
Signature of third inventor

Execution date of U.S. Patent Application

Feb. 14 2014
Date of this assignment

ADDITIONAL INVENTOR(S)

SHII SUZUKI

Name of fourth inventor
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Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

February 17, 2014

MYO FUKAZAWA

Name of fifth inventor

KANAGAWA, JAPAN

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Signature of fifth inventor

Execution date of U.S. Patent Application

Date of this assignment

February 20, 2014

Name of sixth inventor

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

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Execution date of U.S. Patent Application

Date of this assignment

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Execution date of U.S. Patent Application

Date of this assignment

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Execution date of U.S. Patent Application

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